

| Ref # | Hits | Search Query  | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|------|---|---|------------------|---------|------------------|
| L1    | 7281 | (@ad<"20010611") and (chip or die) and (((substrate or sheet or film or frame or pad or paddle) and (mold or molding)) same (force or forcibly or press or lift or push)) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/10/07 11:27 |
| L2    | 3988 | (@ad<"20010611") and (chip or die) and (((substrate or sheet or film or frame or pad or paddle) and (mold or molding)) with(force or forcibly or press or lift or push))  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/10/07 11:25 |
| L3    | 3988 | (@ad<"20010611") and (chip or die) and (((substrate or sheet or film or frame or pad or paddle) and (mold or molding)) with (force or forcibly or press or lift or push)) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/10/07 10:47 |
| L4    | 716  | L3 and (encapsulate or encapsulant or epoxy) and (excision or cut or saw or snip)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/10/07 10:49 |
| L5    | 5    | L3 and (die adj (down or up))   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/10/07 10:49 |
| L6    | 9    | L3 and ((die near (up or down)) with ((force or forcibly or press or lift or push)))  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/10/07 11:26 |
| L7    | 117  | ((die near (up or down)) and pin\$1) with ((force or forcibly or press or lift or push)))   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/10/07 11:27 |
| L8    | 14   | L7 and (@ad<"20010611") and (chip or die) and (mold or molding or encapsulate or encapsulant or epoxy or plastic)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/10/07 11:27 |

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|----|----|--|---|----|-----|------------------|
| L9 | 15 | L7 and (@ad<"20010611") and (chip or die) and (mold or molding or encapsulate or encapsulant or epoxy or plastic or resin) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/10/07 11:28 |
|----|----|--|---|----|-----|------------------|